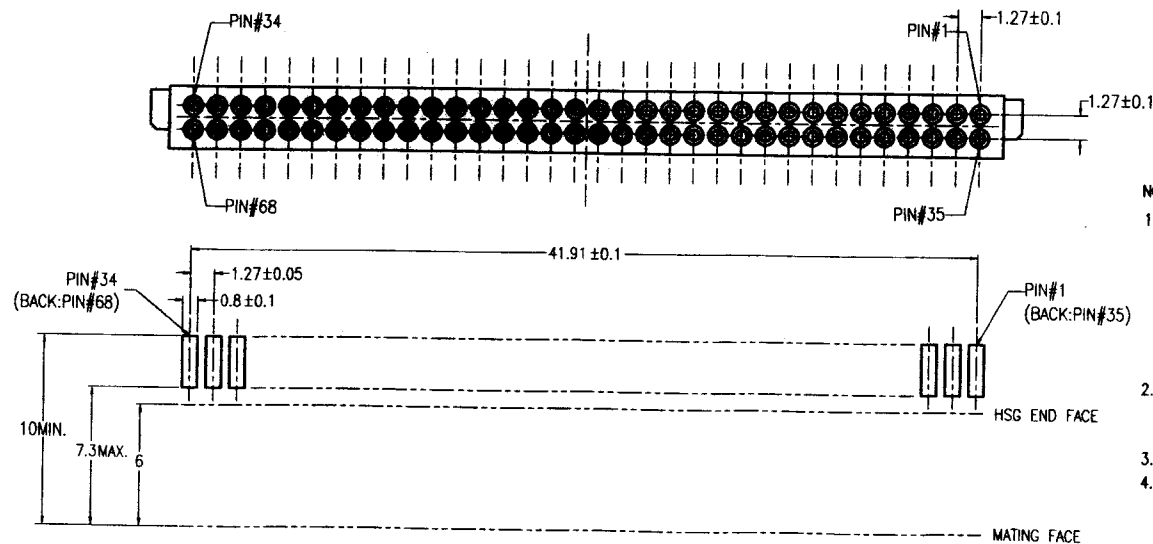
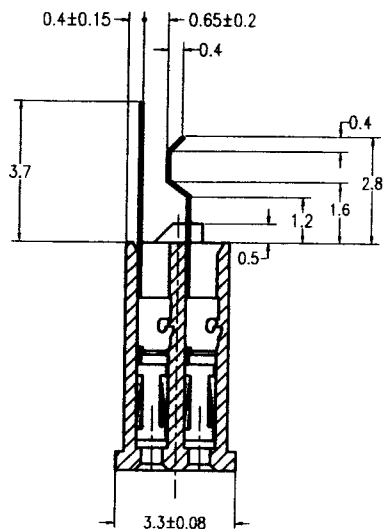
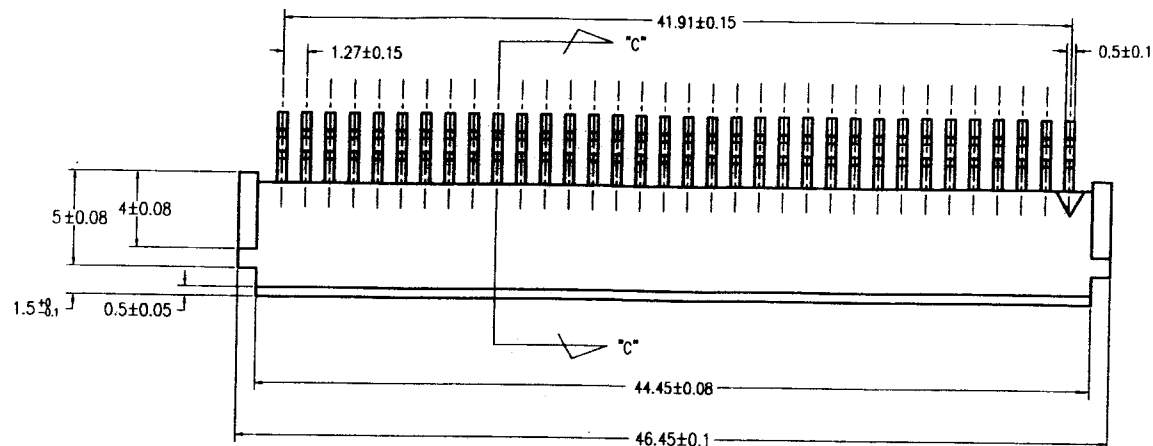
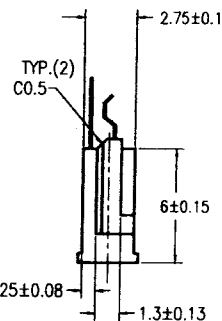


REVISIONS				
REV	DESCRIPTION	ECN	BY	DATE
A	RELEASED	J80050	N.Td	2/26/9



1. MATERIAL
CONTACT : BeCu 0.08t
HSG. : LCP UL94V-0

FINISH (PLATING)
CONTACT : ALL OVER ----- Ni UNDER 0.5 μ m THK.MIN.
SELECTIVE ----- Au PLATING 0.1 μ m THK.MIN.
OVER Pd-Ni PLATING.
SOLDER TAIL ---- TIN LEAD 2.5 μ m THK. MIN.

2. FOR MATING MALE CONN.(HDR./EJECTOR HDR.)
TO APPLY 68 POS. MALE CONN.(HDR./EJECTOR HDR.) BASED ON
JEIDA AND PCMCIA SPECIFICATION.

3. GENERAL TOLERANCE : ± 0.25

4. RECOMMENDED PWB THICKNESS : 0.6 TO 0.85

RECOMMENDED PWB FOOTPRINT LAYOUT

DF-003A REV C